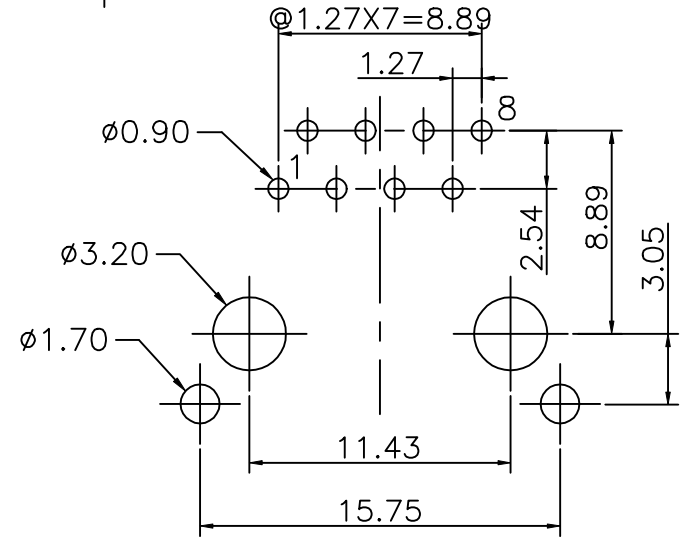
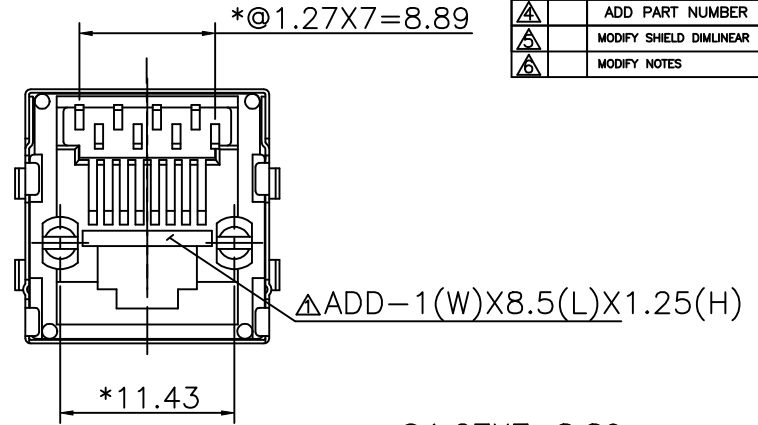
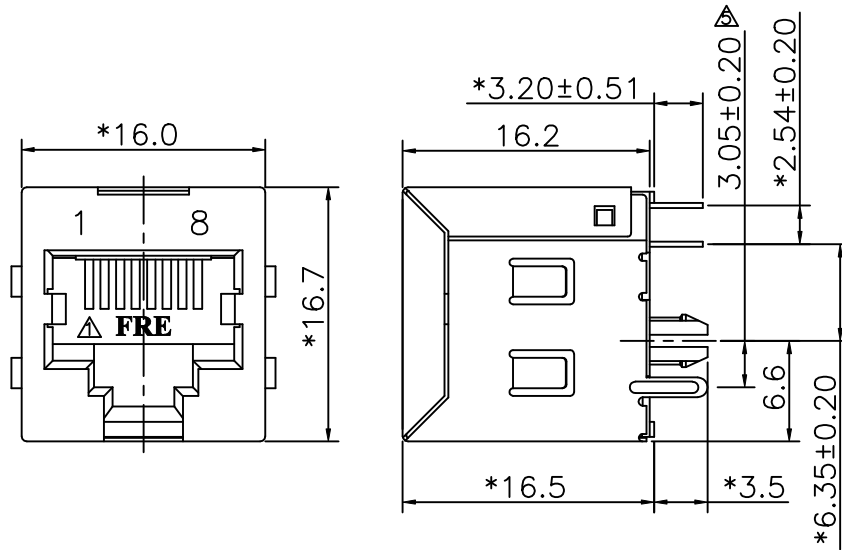


REVISION RECORD				
REV	ECO	DESCRIPTION	DRFT	CHKD
△		Modify Drawing	LFE 4/15/02	
△		ADD PART NUMBER	SAMMY 08/15/02	
△		Modify Drawing	CZH 7/23/03	
△		ADD PART NUMBER	SAMMY 05/18/04	
△		MODIFY SHIELD DIMLINEAR	LUXIN 08/17/04	
△		MODIFY NOTES	Among 10/22/04	



PC Board Layout Component Side Shown

**NOTES:**

**ELECTRICAL:**

- VOLTAGE RATING : 125 VAC RMS.
- CURRENT RATING : 1.5 AMP.
- CONTACT RESISTANCE : 30 MILLIOHMS MAX.
- INSULATION RESISTANCE: 1000 MEGOHMS MIN @ 500 VDC.
- DIELECTRIC STRENGTH : 1000 VAC RMS 60Hz, 1MIN.

**MECHANICAL:**

- HOUSING MATERIAL : GLASS FILLED POLYESTER UL94V-0.
- CONTACT MATERIAL : PHOSPHOR BRONZE t=0.35mm.
- PLATING : GOLD PLATING OVER NICKEL.
- OPERATING LIFE : 750 CYCLES MIN.
- PCB RETENTION PRE-SOLDER : 1 LB MIN.
- PCB RETENTION POST-SOLDER: 10 LBS MIN.

**ENVIRONMENTAL:**

- STORAGE : -40°C TO +85°C.
  - OPERATION: -40°C TO +85°C.
- MATES WITH MODULAR PLUG CONFORMING TO  
FCC PART 68, SUBPART F.

CUL FILE NO. E163191  
PART NUMBER: E5288-3X0X4X

△△ SHIELD PLATING:

GOLD PLATING:

- 1- TIN PLATING,W/ SIDE TABS
- 2- NICKEL PLATING,W/ SIDE TABS
- △ S- TIN PLATING,W/O SIDE TABS
- △ T- NICKEL PLATING,W/O SIDE TABS

- 1- 3u" 2- 6u"
- 3- 15u" 4- 30u"
- 5- 50u"

- 0-A06-0100 (BK)
- 1-A06-0080 (BK)△

← MM (INCH) →		DFTO BASS	DATE 7/8/97	FULL RISE ELECTRONIC CO., LTD	
TOLERANCES EXCEPT AS NOTED		CHKD SAMMY	DATE 2004/11/17		
MFO		DATE		TITLE	
MM		APPLV LUSHENG	DATE 2004/11/17	RJ45 TOP ENTRY PCB MODULAR JACK(DIP TYPE)	
.0 ±0.20 ±		MATERIAL :		DRAWING NO. GE523014	
.00 ±0.15 ±		QT'Y :		/PART NO. SEE NOTE	
.000 ±0.075 ±		FINISH :		SIZE A3	
ANGLES ±		SCALE : 3:1		REV 6	
THIRD ANGLE PROJECTION		DO NOT SCALE DRAWING		SHEET X OF Y	